

5 mm x 7 mm Ceramic Package SMD Oscillator, LVPECL / LVDS



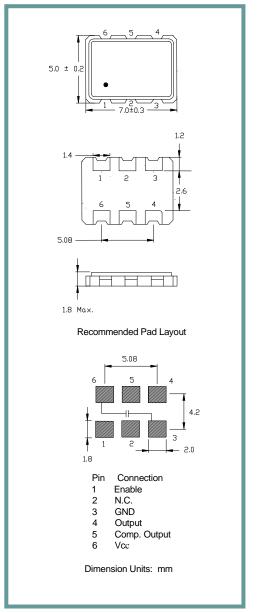
Product Features:

Low Noise Surface Mount Package Reflow Compatible Compatible with Leadfree Processing

Applications:

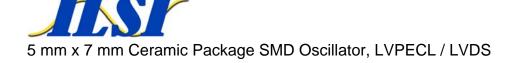
Test Equipment Server & Storage Sonet /SDH

Frequency	1 MHz to 180.000 MHz					
Output Level LVDS LVPECL	Vod = 393 mV Typ., 475 mV Max. '0' = Vcc - 1.63 V Max. '1' = Vcc - 1.02 V Min.					
Duty Cycle	Specify 50% ±10% or ±5% See Table in Part Number Guide					
Rise / Fall Time	0.6 nS Max.					
Output Load LVDS LVPECL	100 Ω Differential 50 Ω to Vcc - 2.0 VDC					
Frequency Stability	See Frequency Stability Table in Part Number Guide (Includes room temperature tolerance and stability over operating temperature)					
Start-up Time	10 mS Max.					
Enable / Disable Time	100 nS Max.					
Supply Voltage	See Input Voltage Table, tolerance ±5 %					
Current	LVDS = 90 mA Max. ***					
	LVPECL = 130 mA Max. ***					
Jitter	<1.0 pS RMS*					
Operating	See Operating Temperature Table in Part Number Guide					
Storage	-55° C to +125° C					



Part Number Guide		Sample Part Number:		ISM98 - 3159BH - 125.000			
Package	Input Voltage	Operating Temperature	Symmetry (Duty Cycle)	Output	Stability (in ppm)	Enable / Disable	Frequency
	3 = 3.3 V	1 = 0° C to +70° C	5 = 45 / 55 Max.	8 = LVDS	**A = ±25	H = Enable	- 125.000 MHz
	7 = 3.0 V	6 = -10° C to +70° C	6 = 40 / 60 Max.	9 = LVPECL	B = ±50		
ISM98 -	2 = 2.7 V	3 = -20° C to +70° C			C = ±100		
	6 = 2.5 V	4 = -30° C to +75° C]	
		2 = -40° C to +85° C					

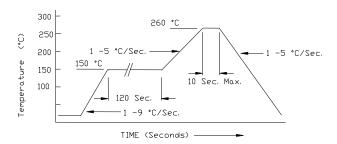
NOTE: A 0.01 µF bypass capacitor is recommended between Vcc (pin 6) and GND (pin 3) to minimize power supply noise.
*Frequency related, for additional information contract your sales representative. ** Not available for all temperature ranges. *** Frequency, supply, and load related parameters.



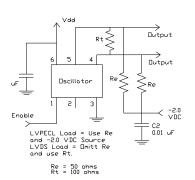


Pb Free Solder Reflow Profile:

Typical Application:



^{*}Units are backward compatible with 240C reflow processes

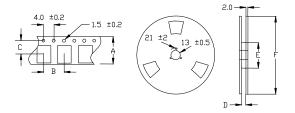


Package Information:

MSL = N.A. (package does not contain plastic, storage life is unlimited under normal room conditions).

Termination = e4 (Au over Ni over W base metalization).

Tape and Reel Information:



Quantity per Reel	1000		
Α	16 +/3		
В	8 +/2		
С	7.5 +/2		
D	17.5 +/-1		
E	50 / 60 / 80		
F	180 / 250		

Environmental Specifications

Thermal Shock	MIL-STD-883, Method 1011, Condition A
Moisture Resistance	MIL-STD-883, Method 1004
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Mechanical Vibration	MIL-STD-883, Method 2007, Condition A
Resistance to Soldering Heat	J-STD-020C, Table 5-2 Pb-free devices (except 2 cycles max)
Hazardous Substance	Pb-Free / RoHS / Green Compliant
Solderability	JESD22-B102-D Method 2 (Preconditioning E)
Terminal Strength	MIL-STD-883, Method 2004, Test Condition D
Gross Leak	MIL-STD-883, Method 1014, Condition C
Fine Leak	MIL-STD-883, Method 1014, Condition A2, R1=2x10-8 atm cc/s
Solvent Resistance	MIL-STD-202, Method 215

Marking

Line 1: ILSI and Date Code (YWW)

Line 2: Frequency

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